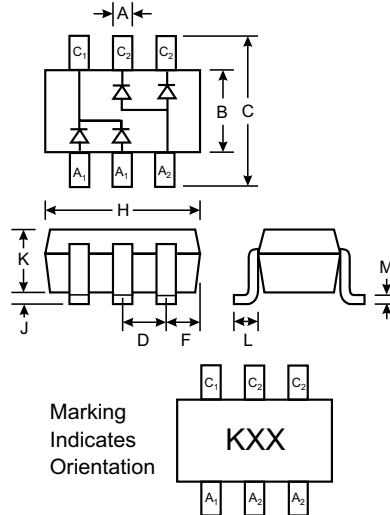


### Features

- Fast Switching Speed
- Ultra-Small Surface Mount Package
- For General Purpose Switching Applications
- High Conductance
- One BAV70 Circuit and One BAW56 Circuit In One Package

### Mechanical Data

- Case: SOT-363, Molded Plastic
- Terminals: Solderable per MIL-STD-202, Method 208
- Polarity: See Diagram
- Marking: KAC
- Weight: 0.006 grams (approx.)



SOT-363		
Dim	Min	Max
A	0.10	0.30
B	1.15	1.35
C	2.00	2.20
D	0.65 Nominal	
E	0.30	0.40
G	1.80	2.20
H	1.80	2.20
J	—	0.10
K	0.90	1.00
L	0.25	0.40
M	0.10	0.25
All Dimensions in mm		

### Maximum Ratings @ $T_A = 25^\circ\text{C}$ unless otherwise specified

Characteristic	Symbol	BAW567DW	Unit
Non-Repetitive Peak Reverse Voltage	$V_{RM}$	100	V
Peak Repetitive Reverse Voltage	$V_{RRM}$	75	V
Working Peak Reverse Voltage	$V_{RWM}$		
DC Blocking Voltage	$V_R$		
RMS Reverse Voltage	$V_{R(RMS)}$	53	V
Forward Continuous Current (Note 1)	$I_{FM}$	300	mA
Average Rectified Output Current (Note 1)	$I_O$	150	mA
Non-Repetitive Peak Forward Surge Current @ $t = 1.0\mu\text{s}$ @ $t = 1.0\text{s}$	$I_{FSM}$	2.0 1.0	A
Power Dissipation (Note 1)	$P_d$	200	mW
Thermal Resistance Junction to Ambient Air (Note 1)	$R_{\theta JA}$	625	K/W
Operating and Storage Temperature Range	$T_j, T_{STG}$	-65 to +150	$^\circ\text{C}$

### Electrical Characteristics @ $T_A = 25^\circ\text{C}$ unless otherwise specified

Characteristic	Symbol	Min	Max	Unit	Test Condition
Maximum Forward Voltage	$V_{FM}$	—	0.715 0.855 1.0 1.25	V	$I_F = 1.0\text{mA}$ $I_F = 10\text{mA}$ $I_F = 50\text{mA}$ $I_F = 150\text{mA}$
Maximum Peak Reverse Current	$I_{RM}$	—	2.5 50 30 25	$\mu\text{A}$ $\mu\text{A}$ $\mu\text{A}$ nA	$V_R = 75\text{V}$ $V_R = 75\text{V}, T_j = 150^\circ\text{C}$ $V_R = 25\text{V}, T_j = 150^\circ\text{C}$ $V_R = 20\text{V}$
Junction Capacitance	$C_j$	—	2.0	pF	$V_R = 0, f = 1.0\text{MHz}$
Reverse Recovery Time	$t_{rr}$	—	4.0	ns	$I_F = I_R = 10\text{mA}$ , $I_{rr} = 0.1 \times I_R, R_L = 100\Omega$

Notes: 1. Valid provided that terminals are kept at ambient temperature.

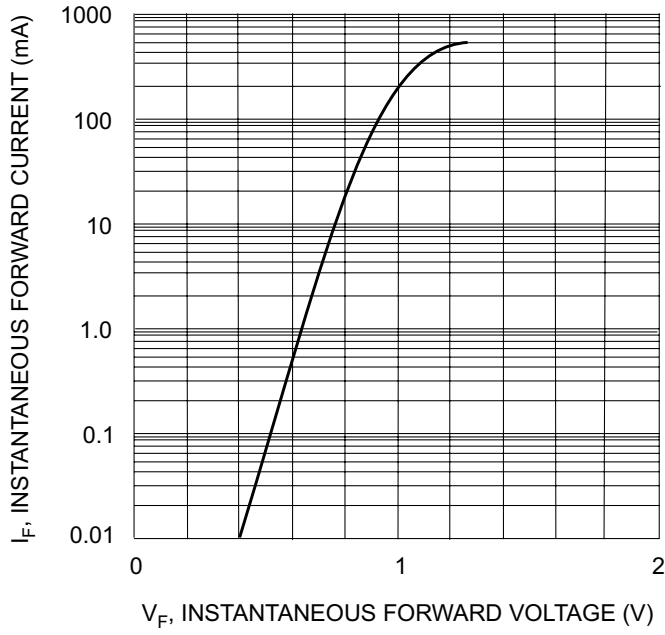


Fig. 1 Forward Characteristics

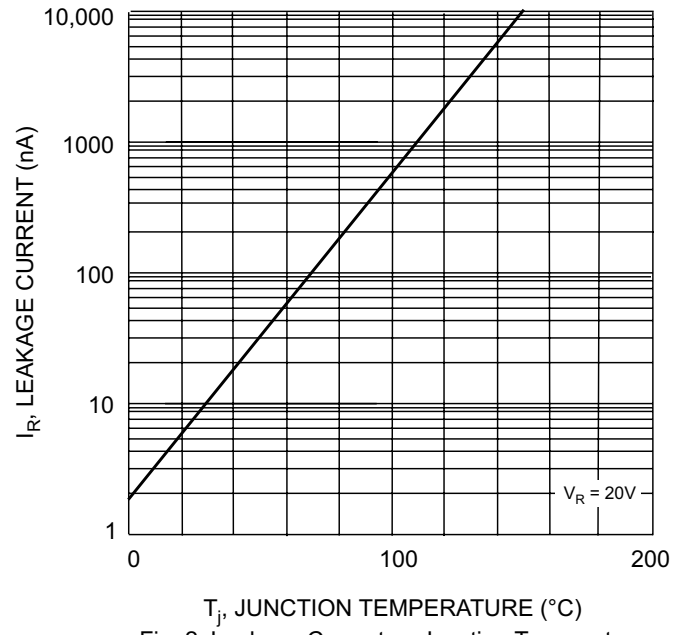


Fig. 2 Leakage Current vs Junction Temperature